

**ABSTRACT**

An undercoat film that prevents copper diffusion and has excellent copper conductor film binding, even when thin. In addition, a material for forming a copper undercoat film, characterized by a compound represented by the general formula:  $(R_1R_2)P-(R)_n-Si(X_1X_2X_3)$ , wherein at least one of  $X_1, X_2$  and  $X_3$  is a hydrolytic group,  $R_1$  and  $R_2$  are alkyl groups,  $R$  denotes a chain-form organic group formed from alkyl groups, aromatic rings or alkyl groups containing aromatic rings, and  $n$  is an integer from 1 to 6.